

IN THE SPECIFICATION

On page 9, lines 11-12, please amend the specification as follows:

~~FIG. 2 is an illustration~~ FIGs. 2a-2e are illustrations showing the first embodiment of the present invention;

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:
forming a cross shaped via in at least one of the conductive layers and in the dielectric layers;
applying a conductive material to exposed portions of at least two conductive layers through the cross shaped via, the conductive material creating an electrical coupling between the conductive layers; and
grounding at least one of the conductive layers to a controlled ground potential;
~~wherein the portions of the conductive layers are exposed by recessing an edge of at least one of the conductive layers and any dielectric layers positioned between the conductive layers to form stepped back edges on the one of the conductive layers and the one or more dielectric layers; the conductive material overhanging an uppermost of the conductive layers;~~
2. (Cancelled)